

pnCCDs: simulations and reality

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- » pnCCDs produced in the MPI semiconductor lab
- » Motivation for a detailed device analysis
- » The mesh experiment
- » Data analysis and pixel reconstruction
- » Comparison of measurements and device simulations
- » Simulations and measurements of photon absorption in the register structure
- » Summary and conclusion



pnCCDs produced in the MPI semiconductor lab

» pnCCD: principle of charge transfer like in conventional MOS-CCD with three registers [1]



- » Basic structure is a double sided pn diode [2] with p+ contacts on both sides of the substrate, MOS-gates define fixed potential of p+ register contacts
 - \rightarrow Depletion of shallow n doped bulk silicon with n+ contact at the rim
 - \rightarrow High quantum efficiency from near Infrared to X-ray
 - \rightarrow Fast parallel column readout with low noise down to 2e-



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pnCCDs produced in the MPI semiconductor lab

- » Different pixel sizes and wafer thicknesses
 - \rightarrow Wafer sizes from 4"/280µm to 6"/450µm for devices of current production
 - \rightarrow Pixel sizes of 150µm, 75µm, 51µm and 36µm with up to 264x264 pixels





» Fully depleted bulk with high back contact voltage (E-field 4000V/cm and more) → Drift dominated charge collection, drift times around 1.5ns



» Electron cloud expands during drift time due to electrostatic repulsion and diffusion; for low X-ray photon energies, diffusion is the dominating effect. → 1e⁻ per 3.65eV: 486e⁻ for W-M (1774eV) or 1236e⁻ for Ti-Kα (4510eV)



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Motivation for a detailed device analysis



Electric potential in pnCCD with 75µm pixels, a region of 100µm width and 20µm depth with four registers is shown.

Voltages of surface contacts and implantation doses + profiles determine el. **》** potential inside pnCCD. Electron cloud is split at potential barrier of pixel.



The mesh experiment [4]

» Scanning of a pixel gives data on response to photon conversion position in pixel \rightarrow scanning with resolution in µm range too difficult, use mesh method!



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Data analysis and pixel reconstruction

» Photons detected as pulse height patterns of one up to four pixels → pulse heights represent spreading of charge cloud over pixels

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- Map of pixels with single events, pixels are bright where holes lie near center of pixel
- Yellow lines are parameterization of moiré pattern: distance, angle and offset to lower left corner define position of the mesh



- Projection of frame data into a "virtual" pixel, the reconstruction of an average pixel
- Map showing the relative amount of collected charge in an area of 3x3 pixels: charge collection function
- Map showing the count rate in an area of 1 pixel: count map



Comparison of measurements and device simulations

» Charge collection function can be simulated as a profile in line and transfer direction



- Simulations have a good accuracy with an error of 4% to max. 10%
- \bullet Charge collection function profile is parameterized as an error function with a specific charge cloud σ
- Error of the simulated σ is below 10%
- Value of σ typically 7µm in studied 75µm pixel device

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» Charge collection function can be simulated as a profile in line and transfer direction



- Simulations have a good accuracy with an error of 4% to max. 10%
- Charge collection function profile is parameterized as an error function with a specific charge cloud σ .
- Error of the simulated σ is below 10%
- Value of σ typically 9µm in studied 51µm pixel device

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Comparison of measurements and device simulations

Depth (time) resolved view of the charge collection simulation shown before: **》** depth [µm] depth [µm] <u>آ</u>60 75µm pixel, depth 20 MPI ← transfer direction 25 semiconductor laboratory of the 40 40 Max-Planck-Institutes for 30 30 30 physics and 20 20 20 extraterrestrial physics 10 10 10 140 width [µm] 140 width [µm] 100 120 100 120 120 140 width [μm] 100 electron density [1e+9cm⁻³] electron density [1e+9cm⁻³] electron density [1e+9cm⁻³] depth [um] 51µm pixel, depth 20 dept 50 ← transfer direction 20 40 40 40 30 30 30 20 20 20 10 10 10 100 width [µm] 100 width [µm] 80 80 100 width [μm] 60 80 60 60 electron density [1e+9cm⁻³ electron density [1e+9cm⁻³ electron density [1e+9cm⁻³

 \bullet Simulations shown here are for a photon $\mbox{ energy of 4.5 keV}$ / Ti-Ka

• Separation of charge cloud in a depth of approx. 1/3 pixel size = width of one register including the MOS-gate

»

structure

The thicknesses and widths

Photon absorption in the register structure

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Analyze the depth of insensitive layers below MOS-gates and in p+ contacts

absorption model of the register structure

absorption model combined with min coverage map in simulation

 Absorption profile is created with geometry and material data of known layers and assumptions on insensitive regions

transmission

- Absorption profile is extended to absorption map of a pixel
- Pixel absorption map is combined with measured map of hole positions in Monte-Carlo simulation to create a count map
- Measured and simulated count maps are subtracted to evaluate the square of the difference

Photon absorption in the register structure

- » Lowest square difference of count map data and simulations gives the best fit thicknesses of the insensitive layers for different X-ray energies
- » Thickness of insensitive p+ layer is extrapolated from technology data

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Summary and conclusion

- » Successful measurements of charge collection and absorption of photons in the front side structure
- » New mesh data analysis method was developed and successfully tested
- » Charge collection function can be simulated with an accuracy better than 10%
- » σ of simulated charge collection function also has an accuracy better than $10\% \rightarrow$ position reconstruction based on simulations is better than 2.5µm
- » Simulations of front side absorption give results for the thickness of an insensitive layer below the MOS-gates → results for different X-ray energies are consistent within an error of 0.5µm

Special thanks to the technology staff and the electronics group of the semiconductor lab!

1) Strüder L., Bräuninger H., et al., Rev. Sci. Instrum. 68 (1997) 4271.

- 2) Rehak P., Gatti E., et al., NIMA 235 (1985) 224.
- 3) N. Meidinger, et al., NIMA 512 (2003) 341.
- 4) H. Tsunemi, K. Yoshita, S. Kitamoto, Jpn. J. Appl. Phys. 36 (1997) 2906.